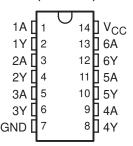
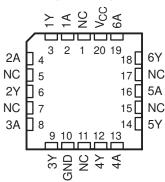
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}

SN54HC14 ... J OR W PACKAGE SN74HC14 ... D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t_{pd} = 11 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max





NC - No internal connection

description/ordering information

These Schmitt-trigger devices contain six independent inverters. They perform the Boolean function $Y = \overline{A}$ in positive logic.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC14N	SN74HC14N
		Tube of 50	SN74HC14D	
	SOIC - D	Reel of 2500	SN74HC14DR	HC14
–40°C to 85°C		Reel of 250	SN74HC14DT	
	SOP - NS	Reel of 2000	SN74HC14NSR	HC14
	SSOP – DB	Reel of 2000	SN74HC14DBR	HC14
		Tube of 90	SN74HC14PW	
	TSSOP - PW	Reel of 2000	SN74HC14PWR	HC14
		Reel of 250	SN74HC14PWT	
	CDIP – J	Tube	SNJ54HC14J	SNJ54HC14J
-55°C to 125°C	CFP – W	Tube	SNJ54HC14W	SNJ54HC14W
	LCCC – FK	Tube	SNJ54HC14FK	SNJ54HC14FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	٧
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	Α
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	Α
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	Α
Continuous current through V _{CC} or GND±50 m/	
Package thermal impedance, θ_{JA} (see Note 2): D package	W
DB package 96°C/V	W
N package 80°C/V	W
NS package 76°C/V	W
PW package 113°C/V	W
Storage temperature range, T _{stg} 65°C to 150°C	С

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54HC14			SN74HC14			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	2	5	6	2	5	6	V
VI	Input voltage	0		VCC	0		VCC	٧
VO	Output voltage	0		VCC	0		VCC	٧
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752	TEST CONDITIONS		.,	T _A =		λ = 25°C		SN54HC14		SN74HC14	
PARAMETER	TEST CC	DNDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	0.7	1.2	1.5	0.7	1.5	0.7	1.5		
V _{T+}			4.5 V	1.55	2.5	3.15	1.55	3.15	1.55	3.15	V
			6 V	2.1	3.3	4.2	2.1	4.2	2.1	4.2	
			2 V	0.3	0.6	1	0.3	1	0.3	1	
V _T _			4.5 V	0.9	1.6	2.45	0.9	2.45	0.9	2.45	V
			6 V	1.2	2	3.2	1.2	3.2	1.2	3.2	
			2 V	0.2	0.6	1.2	0.2	1.2	0.2	1.2	
V _{T+} - V _{T-}		4.5 V	0.4	0.9	2.1	0.4	2.1	0.4	2.1	V	
'' '			6 V	0.5	1.3	2.5	0.5	2.5	0.5		2.5
	VI = VIH or VIL	I _{OH} = -20 μA	2 V	1.9	1.998		1.9		1.9		
			4.5 V	4.4	4.499		4.4		4.4		
VOH			6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34	
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			2		40		20	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

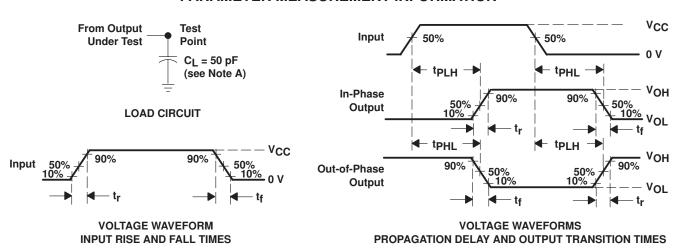
DADAMETED	FROM	то	V	T,	T _A = 25°C SN54HC1		HC14	SN74HC14			
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		55	125		190		155	
tpd	Α	Υ	4.5 V		12	25		38		31	ns
			6 V		11	21		32		26	
			2 V		38	75		110		95	
tţ		Υ	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per inverter	No load	20	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- C. The outputs are measured one at a time, with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





28-Feb-2005





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
5962-8409101VCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
5962-8409101VDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
84091012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8409101CA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
8409101DA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/65702BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/65702BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN54HC14J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN74HC14D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC14DBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC14DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC14DT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC14N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC14N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74HC14NS	ACTIVE	SO	NS	14		Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC14NSLE	OBSOLETE	SO	NS	14		None	Call TI	Call TI
SN74HC14NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC14PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC14PWLE	OBSOLETE	TSSOP	PW	14		None	Call TI	Call TI
SN74HC14PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC14PWT	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC14FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC14J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54HC14W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

28-Feb-2005

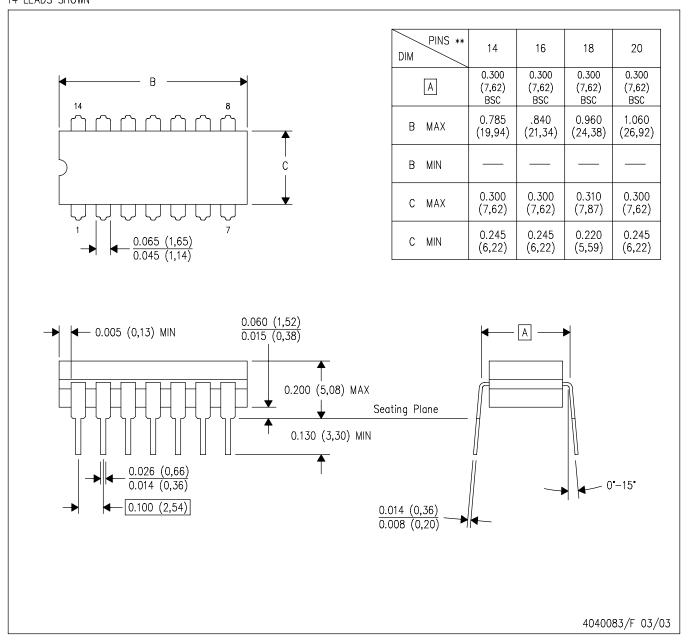
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

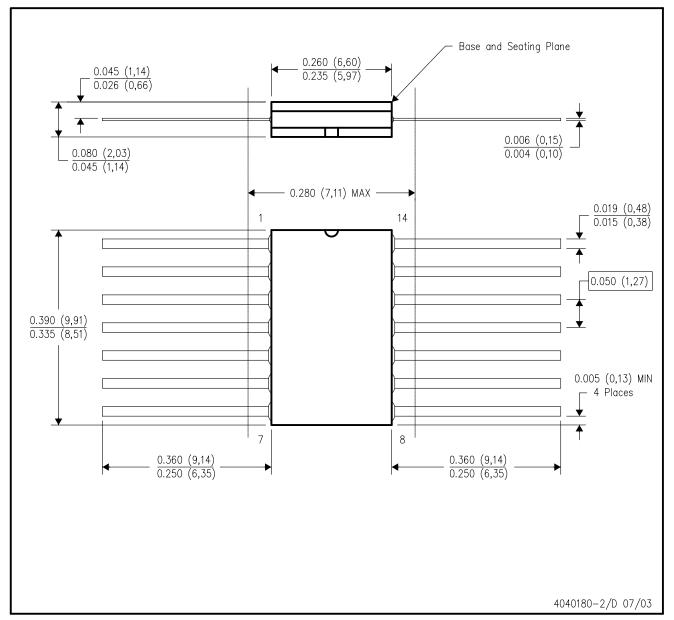
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES: A. All linear

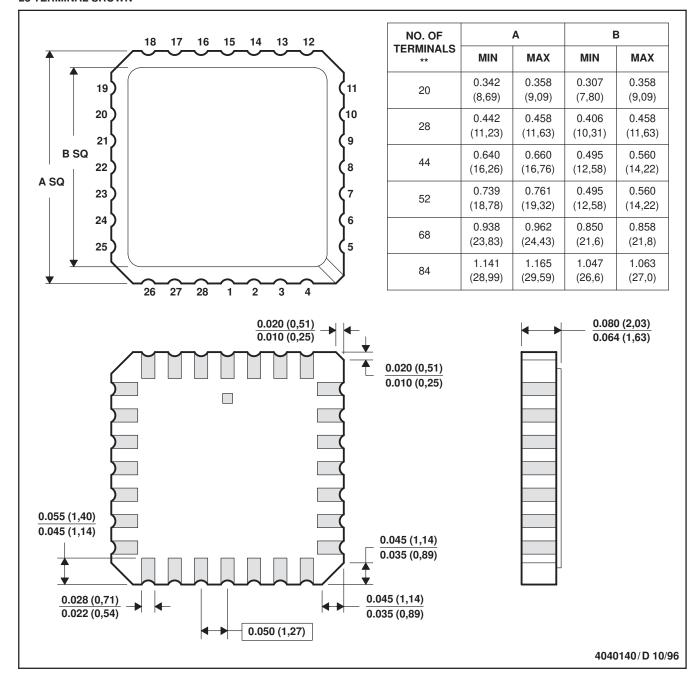
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

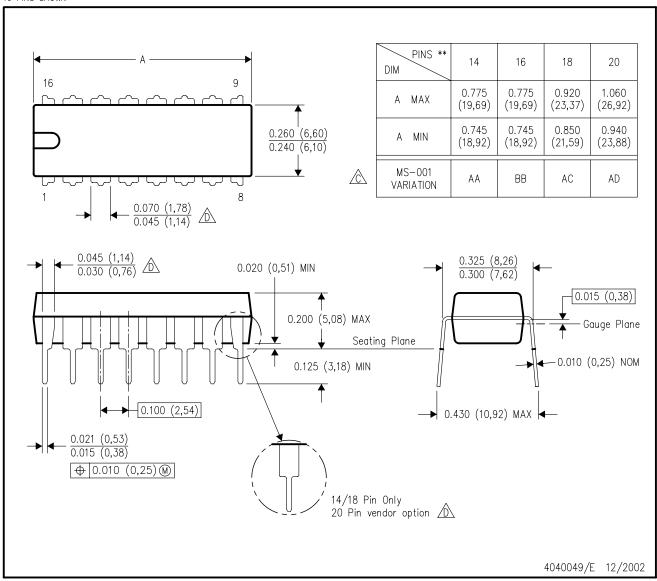
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

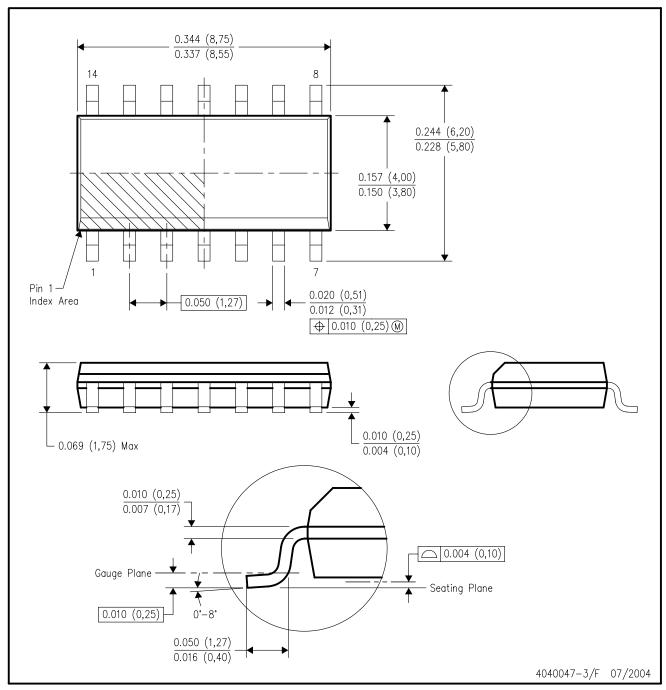


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.

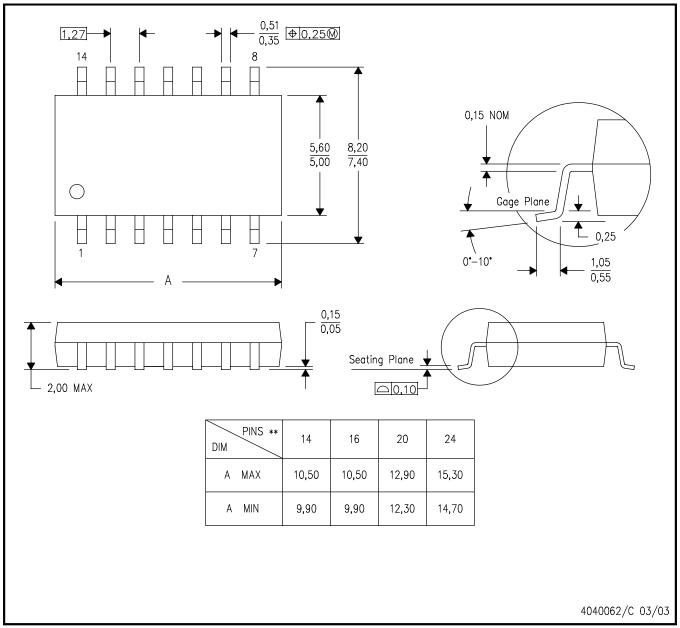


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



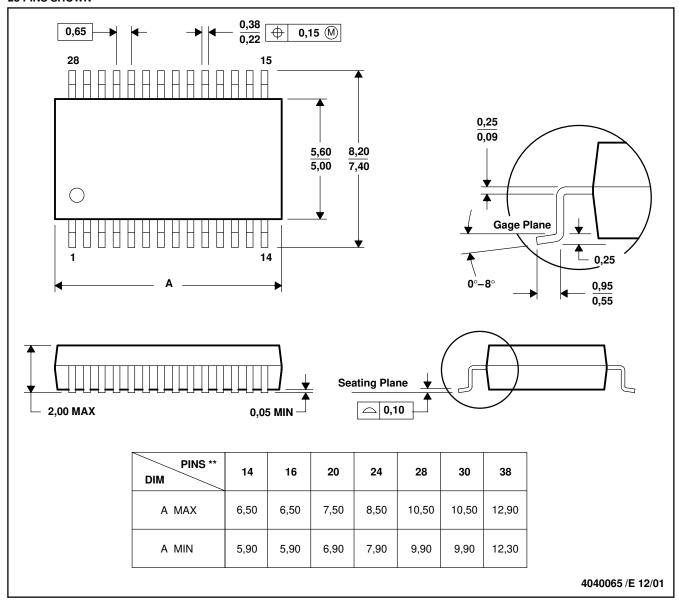
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

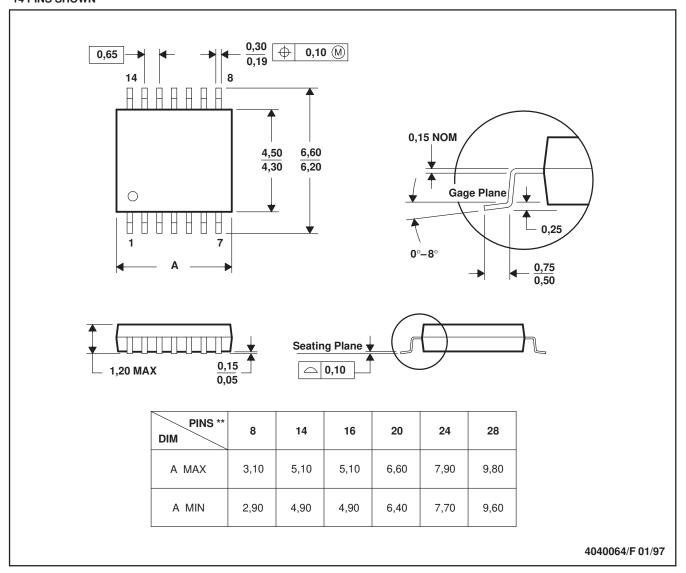
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated